

Maximum Rating

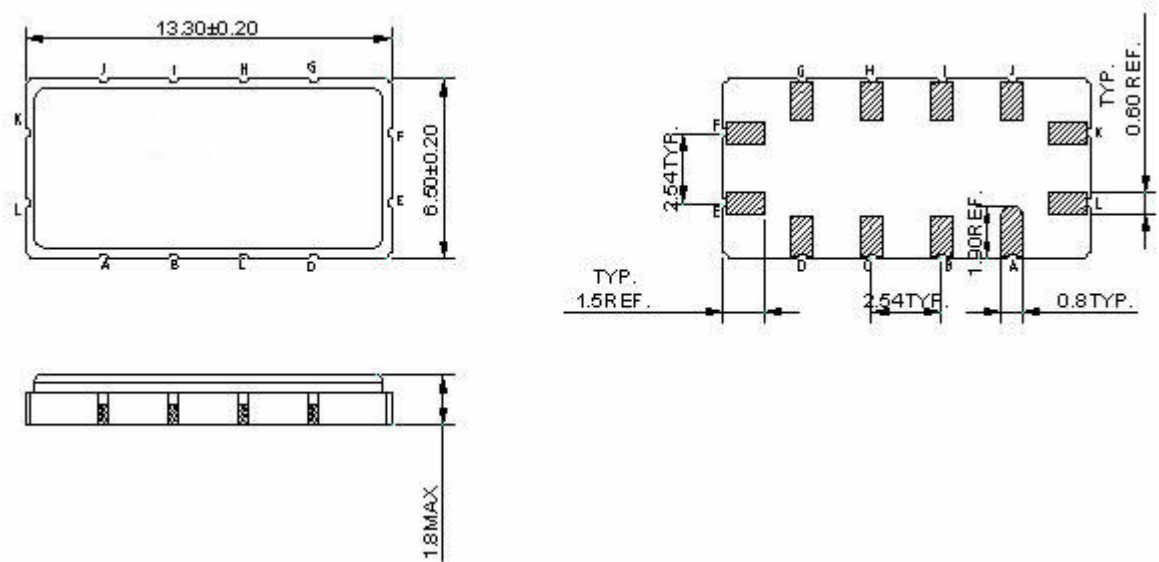
- 0. Maximum Input Power: 10 dBm
- 1. Operating Temperature: -40 °C ~ +85 °C
- 2. Storage Temperature: -40 °C ~ +85 °C

Electrical Characteristics

- 1. Ambient Temperature: 25 °

Characteristics		Value			Note	
		Min.	Typ.	Max.		
Center frequency	F _C MHz	-	140.0	-	-	
Maximum Insertion loss	I.L. dB	-	9.2	10.5	-	
1dB Bandwidth	MHz	18.4	20.8	-	-	
3dB Bandwidth	MHz	20.0	21.8	-	-	
35dB Bandwidth	MHz	-	25.5	26.4	-	
Passband Ripple (within 130.9~149.1MHz)	dB	-	0.75	1.00	-	
Group Delay Ripple (within 130.9~149.1MHz)	nS	-	115	150	-	
Absolute Group Delay	uS	-	1.05	-	-	
Input VSWR (within 130.9~149.1MHz)	dB	-	2.0	2.5	-	
Output VSWR (within 130.9~149.1MHz)	dB	-	1.7	2.3	-	
Temp Coefficient	ppm/° C	-	-93	-	-	
Attenuation:(Reference level from minimum insertion loss)						
1)	10 MHz~ 90 MHz	dB	35	62	-	-
2)	190 MHz~120MHz	dB	40	54	-	-
3)	120MHz ~ 126.8 MHz	dB	35	42	-	-
4)	154.7MHz ~ 160MHz	dB	35	45	-	-
5)	160MHz ~ 190 MHz	dB	40	43	-	-
6)	190MHz ~800MHz	dB	35	62	-	-

Outline Drawing



Pin configuration

- #K RF Input
- #L RF Input ground
- #E RF Output
- #F RF Output ground
- #A, B, C, D, G, H, I, J To be ground

Frequency Characteristics

1. S21 Response

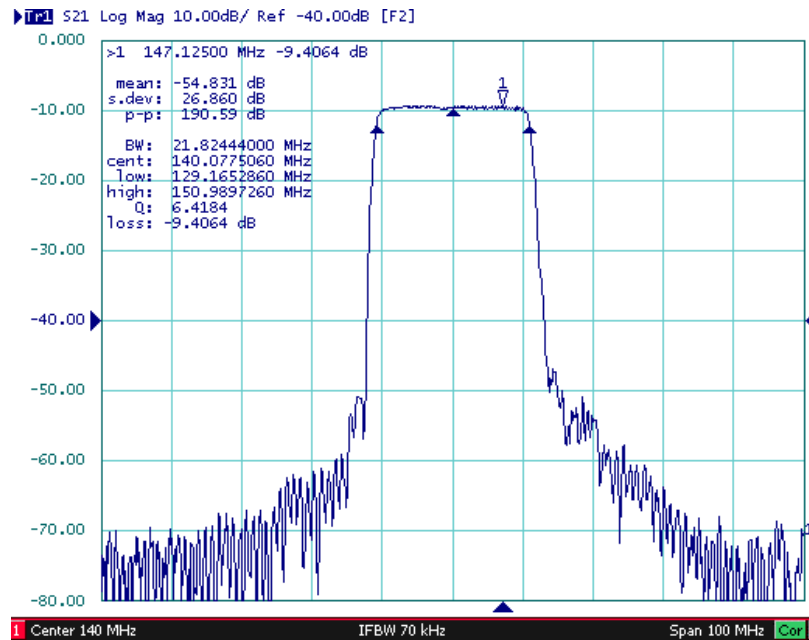


Fig. 1 S21 Response Horizontal: 10MHz/Div; Vertical: 10dB/Div

2. Pass band Ripple

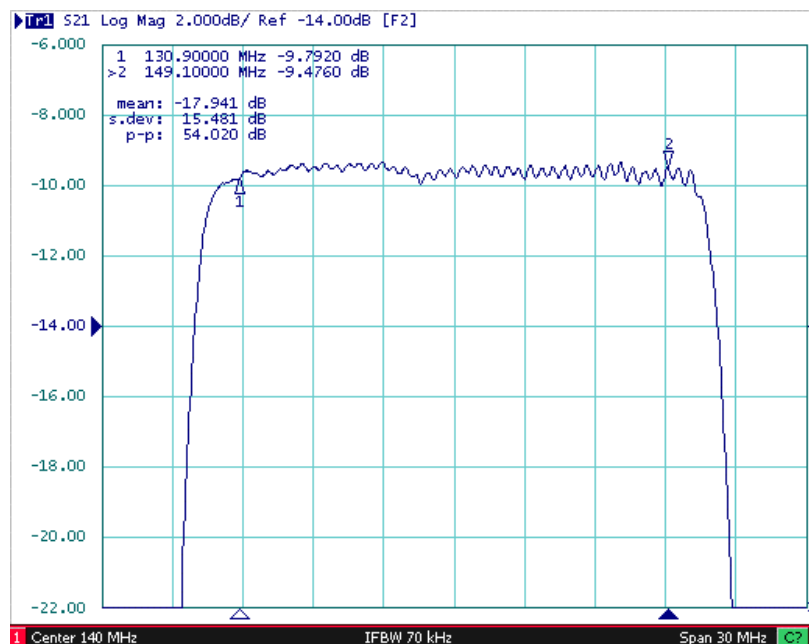


Fig. 2 Inband ripple Horizontal: 3MHz/Div; Vertical: 2dB/Div

3. Group Delay Ripple

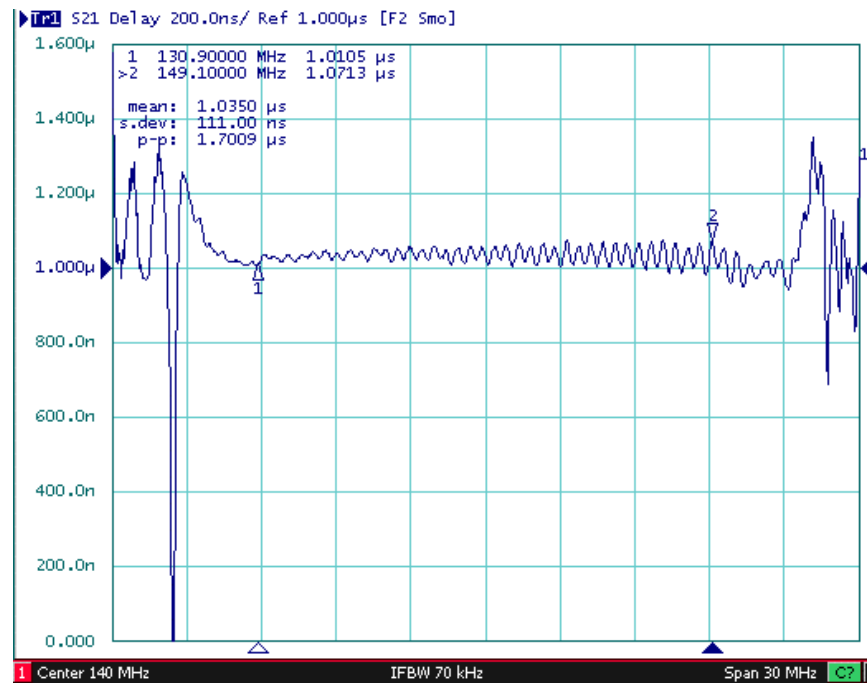


Fig. 3 Group Delay Horizontal: 3MHz/Div; Vertical: 200nS/Div

4. Wide band Response

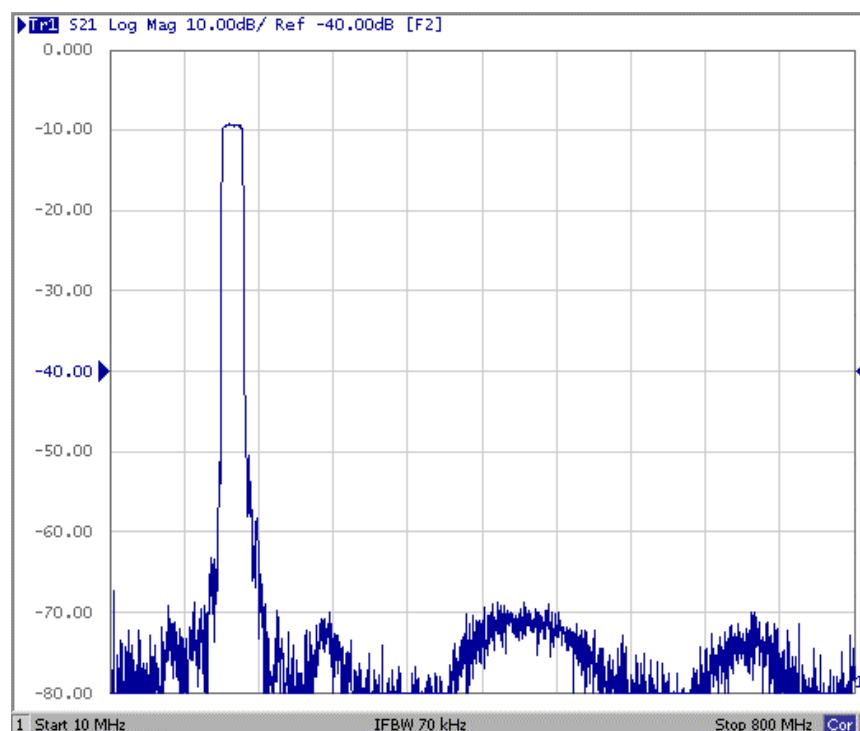
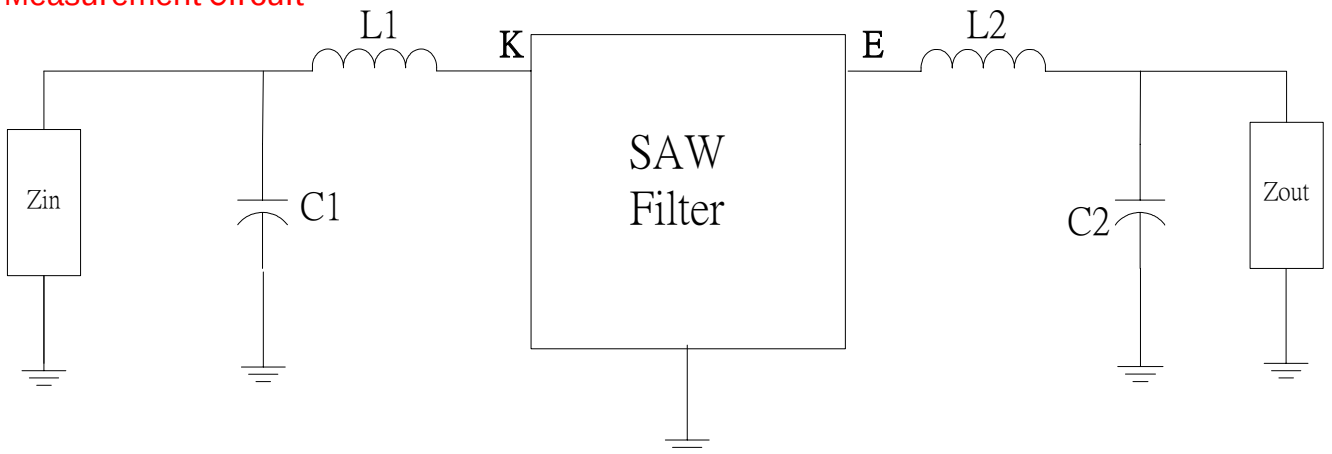


Fig. 3 Wide Band Horizontal: 10~800MHz; Vertical: 10dB/Div

Measurement Circuit

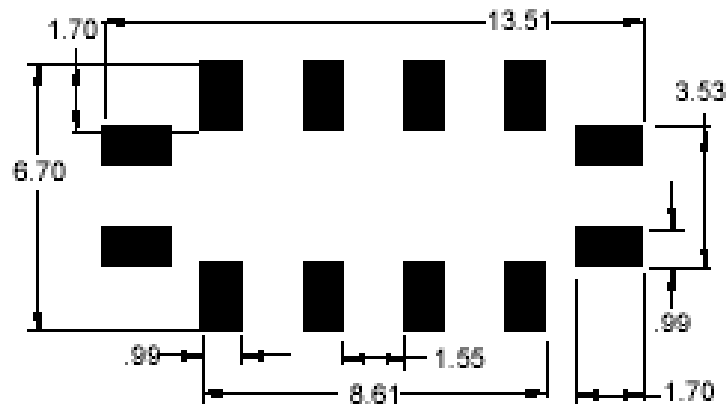


$$Z_{in}=Z_{out}= 50 \text{ ohm}$$

$$L1=92\text{nH}, C1=22\text{pF}, L2=92\text{nH}, C2=33\text{pF}$$

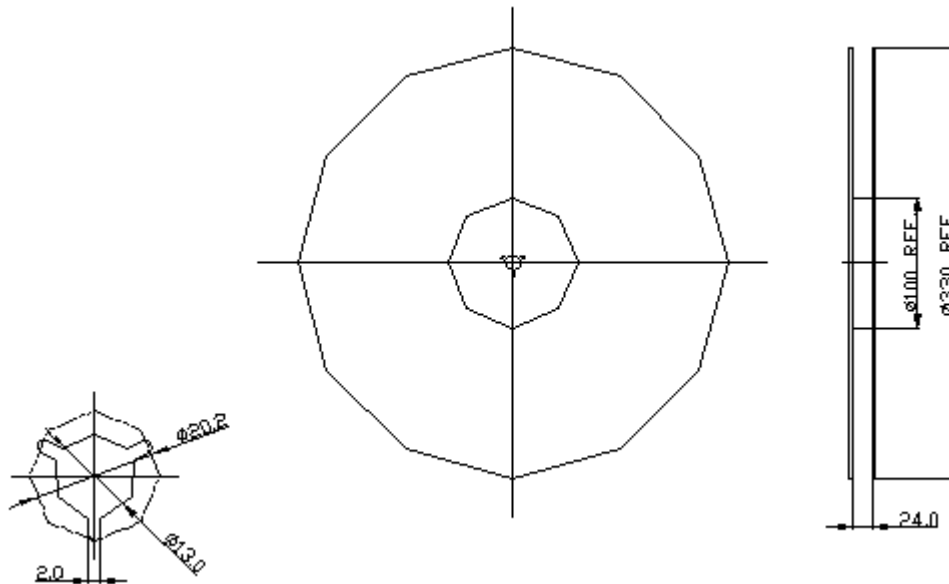
Note: The matching structure will change according to different test fixture.

PCB FootPrint

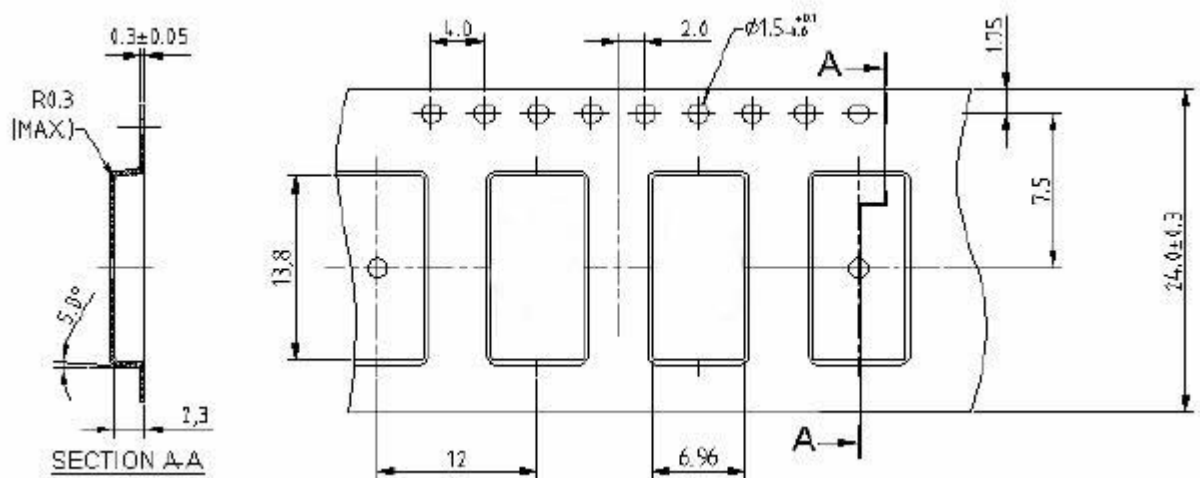


Packing

(1). REEL DIMENSION



(2). TAPE DIMENSION



Recommended Reflow Profile

